

High-performance polishing materials for glass

MIREK™

Application

- Polishing materials for liquid crystal glass, hard disk, photomask, etc

Summary

- Enables high-rate, low-damage processing using CeO₂ abrasives
- Offers a wide range of products suitable for each process, from primary polishing to final finishing
- Tailor-made solutions through various additive selection



Powder



Slurry

Product name	Properties	Average particle size (μm)	Main applications
		Laser diffraction	
HL05	Powder	0.5~0.9	For final polishing
HL10		0.8~1.3	For final polishing
HL21		1.0~1.4	For final polishing
HL30		1.2~1.7	For primary polishing
HL40		1.5~2.3	For primary polishing
HL030CS	Slurry	0.2~0.3	For final polishing
HL020CS		0.1~0.2	For final polishing
K020C		0.08~0.15	For final polishing /Alternatives to colloidal silica /Developed products

※The above data are representative values and not standard values.



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